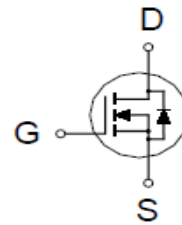
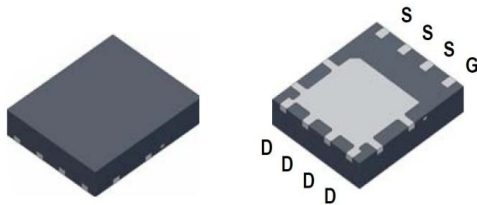


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PRODUCT SUMMARY

$V_{(BR)DSS}$	$R_{DS(ON)}$	I_D
30V	8m Ω @ $V_{GS} = 10V$	46A



PDFN 5X6P

ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ\text{C}$ Unless Otherwise Noted)

PARAMETERS/TEST CONDITIONS		SYMBOL	LIMITS	UNITS
Drain-Source Voltage		V_{DS}	30	V
Gate-Source Voltage		V_{GS}	± 20	V
Continuous Drain Current ³	$T_c = 25^\circ\text{C}$	I_D	46	A
	$T_c = 100^\circ\text{C}$		29	
Pulsed Drain Current ¹		I_{DM}	120	
Continuous Drain Current	$T_A = 25^\circ\text{C}$	I_D	12	
	$T_A = 70^\circ\text{C}$		9.7	
Avalanche Current		I_{AS}	20	
Avalanche Energy	$L = 0.1\text{mH}$	E_{AS}	20	mJ
Power Dissipation	$T_c = 25^\circ\text{C}$	P_D	30	W
	$T_c = 100^\circ\text{C}$		12	
Power Dissipation	$T_A = 25^\circ\text{C}$	P_D	2.1	W
	$T_A = 70^\circ\text{C}$		1.3	
Operating Junction & Storage Temperature Range		T_J, T_{stg}	-55 to 150	$^\circ\text{C}$

THERMAL RESISTANCE RATINGS

THERMAL RESISTANCE	SYMBOL	TYPICAL	MAXIMUM	UNITS
Junction-to-Ambient ²	$R_{\theta JA}$		59	$^\circ\text{C} / \text{W}$
Junction-to-Case	$R_{\theta JC}$		4.1	

¹Pulse width limited by maximum junction temperature.

²The value of $R_{\theta JA}$ is measured with the device mounted on 1in² FR-4 board with 2oz. Copper, in a still air environment with $T_A = 25^\circ\text{C}$.

³Package limitation current is 20A.

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ELECTRICAL CHARACTERISTICS (T_J = 25 °C, Unless Otherwise Noted)

PARAMETER	SYMBOL	TEST CONDITIONS	LIMITS			UNITS
			MIN	TYP	MAX	
STATIC						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = 250\mu A$	30			V
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\mu A$	1.3	1.8	2.3	
Gate-Body Leakage	I_{GSS}	$V_{DS} = 0V, V_{GS} = \pm 20V$			± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 24V, V_{GS} = 0V$			1	μA
		$V_{DS} = 20V, V_{GS} = 0V, T_J = 55^\circ C$			10	
Drain-Source On-State Resistance ¹	$R_{DS(ON)}$	$V_{GS} = 4.5V, I_D = 12A$		7.9	12	m Ω
		$V_{GS} = 10V, I_D = 12A$		5.8	8	
Forward Transconductance ¹	g_{fs}	$V_{DS} = 5V, I_D = 12A$		48		S
DYNAMIC						
Input Capacitance	C_{iss}	$V_{GS} = 0V, V_{DS} = 15V, f = 1MHz$		745		pF
Output Capacitance	C_{oss}			144		
Reverse Transfer Capacitance	C_{rss}			84		
Gate Resistance	R_g	$V_{GS} = 0V, V_{DS} = 0V, f = 1MHz$		3.3		Ω
Total Gate Charge ²	Q_g	$V_{GS} = 10V$		15.4		nC
		$V_{GS} = 4.5V$		8.4		
Gate-Source Charge ²	Q_{gs}	$V_{DS} = 15V,$ $V_{GS} = 10V, I_D = 12A$		2		
Gate-Drain Charge ²	Q_{gd}			4.6		
Turn-On Delay Time ²	$t_{d(on)}$	$V_{DS} = 15V,$ $I_D \cong 12A, V_{GS} = 10V, R_{GEN} = 6\Omega$		22		nS
Rise Time ²	t_r			19		
Turn-Off Delay Time ²	$t_{d(off)}$			38		
Fall Time ²	t_f			20		
SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS ($T_J = 25^\circ C$)						
Continuous Current ³	I_S				25	A
Forward Voltage ¹	V_{SD}	$I_F = 12A, V_{GS} = 0V$			1.2	V
Reverse Recovery Time	t_{rr}	$I_F = 12A, di_F/dt = 100A / \mu S$		15.7		nS
Reverse Recovery Charge	Q_{rr}			4.4		nC

¹Pulse test : Pulse Width ≤ 300 μsec, Duty Cycle ≤ 2%.

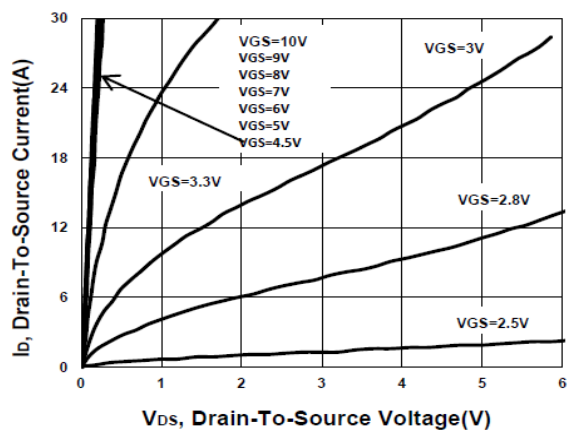
²Independent of operating temperature.

³Package limitation current is 20A.

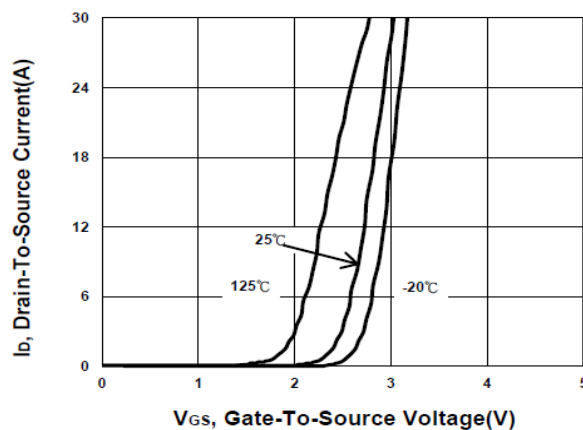
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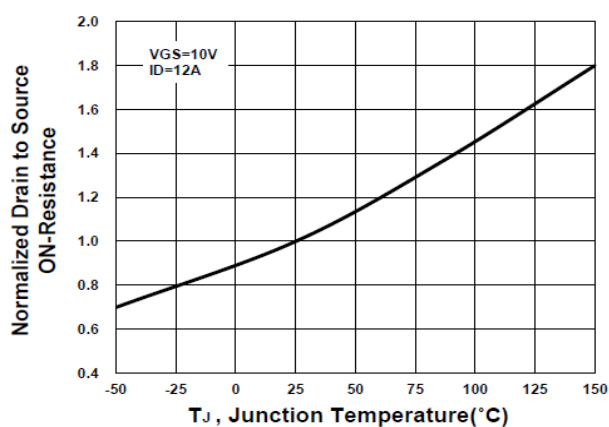
Output Characteristics



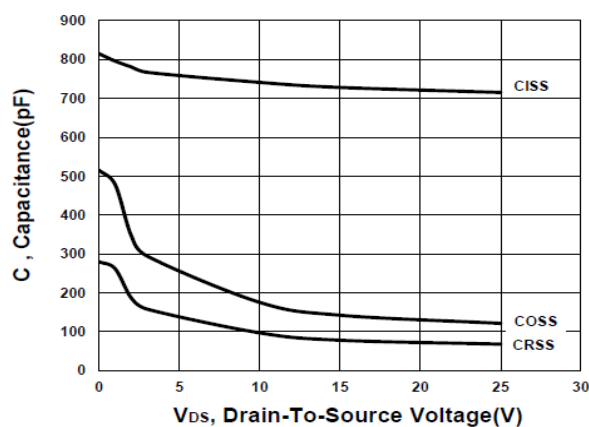
Transfer Characteristics



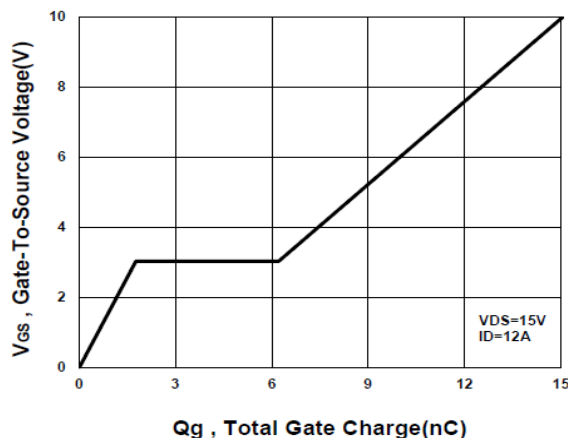
On-Resistance VS Temperature



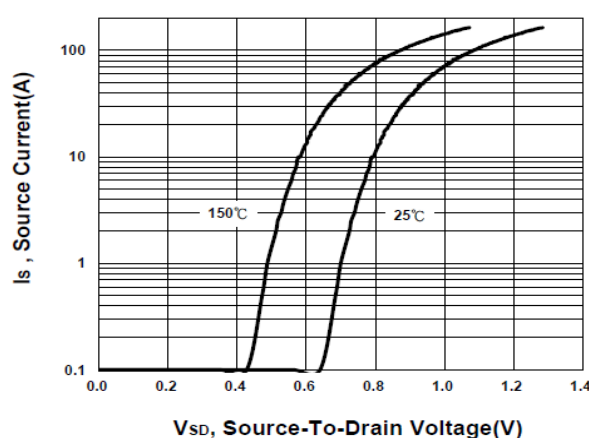
Capacitance Characteristic



Gate charge Characteristics



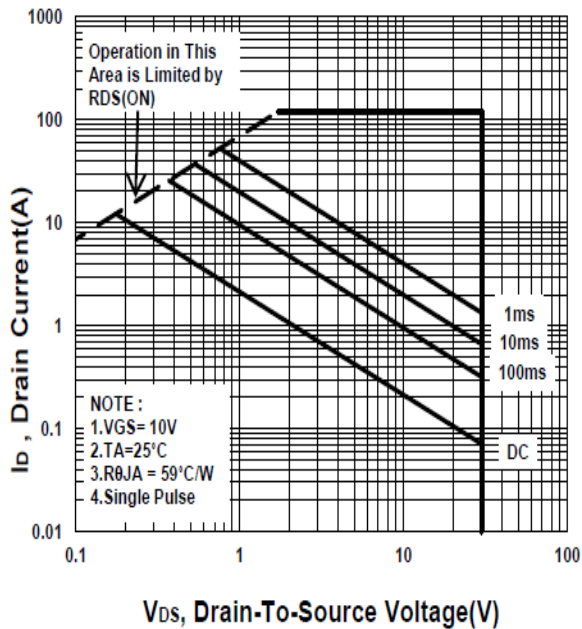
Source-Drain Diode Forward Voltage



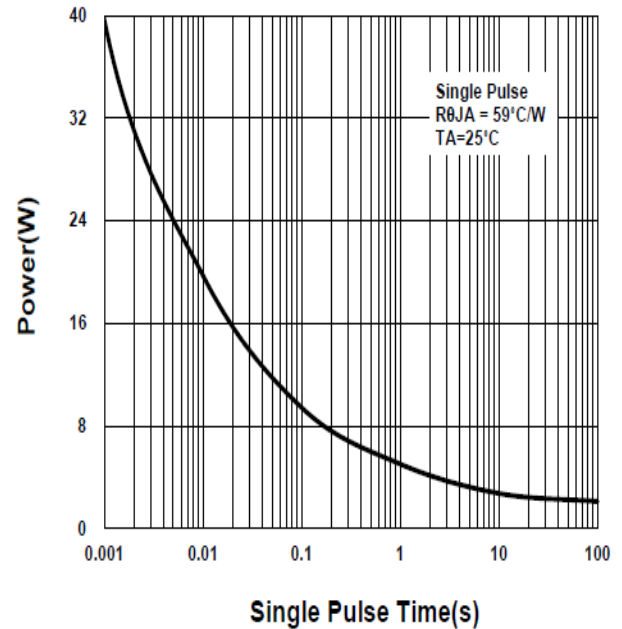
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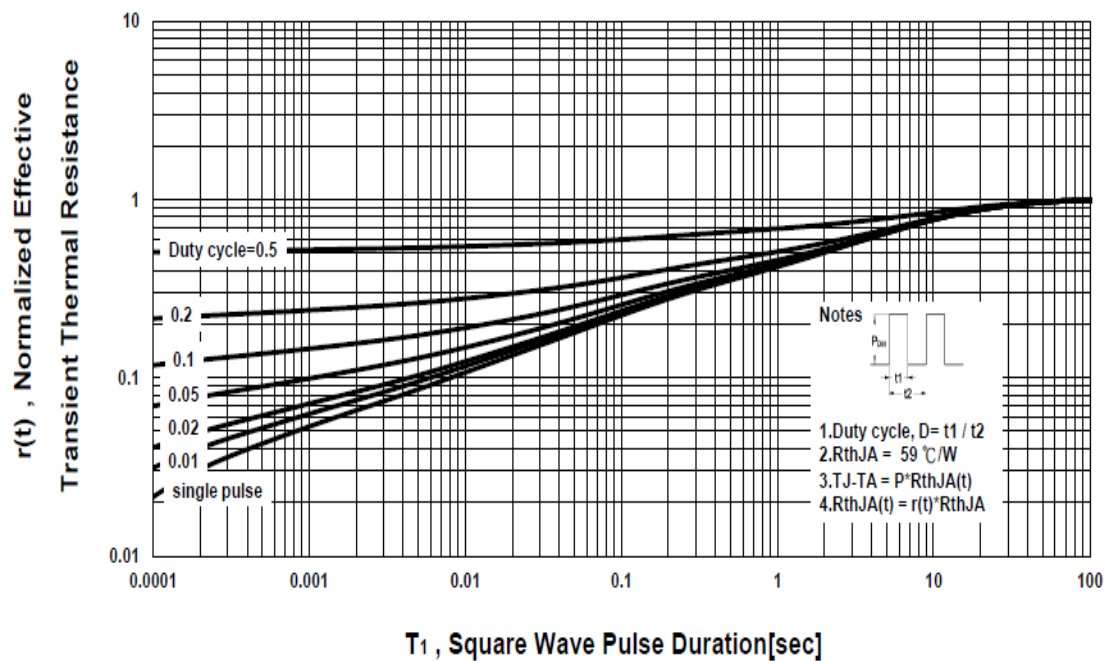
Safe Operating Area



Single Pulse Maximum Power Dissipation



Transient Thermal Response Curve



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PDFN 5x6P MECHANICAL DATA

Dimension	mm			Dimension	mm		
	Min.	Typ.	Max.		Min.	Typ.	Max.
A	4.8		5.15	J	3.33		3.78
B	5.44		5.9	K	0.9		
C	5.9		6.35	L	0.35		0.712
D	0.33		0.51	M	0°		12°
E		1.27		N	4.8		5.5
F	0.8		1.25	O	0.05		0.3
G	0.15		0.34	P	0.06		0.2
H	3.61		4.31	S	3.69		4.19
I	0.35		0.71				

